

Title (en)  
ELECTROLESS PLATING BASE AGENT

Title (de)  
BASISMITTEL FÜR STROMLOSE PLATTIERUNG

Title (fr)  
AGENT DE BASE POUR DÉPÔT AUTOCATALYTIQUE

Publication  
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Application  
**EP 13837102 A 20130912**

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Abstract (en)  
[origin: EP2896720A1] It is an object of the present invention to provide a novel primer for use in pretreatment steps in electroless plating which is environmentally friendly, by which process is easy with fewer steps, and which can realize cost reduction. A primer for forming a metal plating film on a base material by electroless plating, the primer comprising: a hyperbranched polymer having an ammonium group at a molecular terminal and a weight-average molecular weight of 500 to 5,000,000; a metal fine particle; and an alkoxysilane.

IPC 8 full level  
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Citation (search report)

- [A] EP 1491656 A1 20041229 - ROHM & HAAS ELECT MAT [US]
- [A] US 2008248211 A1 20081009 - GONZALEZ SERGIO [US], et al
- See also references of WO 2014042215A1

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